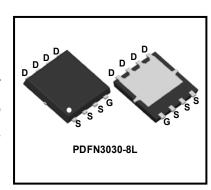


# 100V N-Channel Enhancement Mode Power MOSFET

# **Description**

WMQ175N10LG2 uses Wayon's 2<sup>nd</sup> generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



#### **Features**

- $V_{DS} = 100V$ ,  $I_D = 30A(Silicon Limited)$ 
  - $R_{DS(on)}$  < 17m $\Omega$  @  $V_{GS}$  = 10V
  - $R_{DS(on)}$  < 24m $\Omega$  @  $V_{GS}$  = 4.5V
- Green Device Available
- 100% EAS Guaranteed
- Low Gate Charge
- High Speed Power Switching, Logic Level

# **Applications**

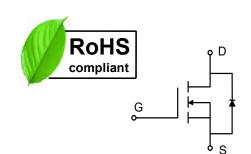
- Synchronous Rectification
- DC/DC Converter
- Power Management Switches

## **Absolute Maximum Ratings**

Parameter		Symbol	Value	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current¹(Silicon Limited)	T <sub>C</sub> =25℃	- ID	30	А	
	T <sub>C</sub> =100°C		18.5		
Pulsed Drain Current <sup>2</sup>		Ірм	120	Α	
Single Pulse Avalanche Energy³		EAS	100	mJ	
Total Power Dissipation <sup>4</sup>	Tc=25°C	P <sub>D</sub>	65.8	W	
Operating Junction and Storage Temperature Range		TJ, TSTG	-55 to 150	°C	

### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	Reja	58	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	R <sub>eJC</sub>	1.9	°C/W





### Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics				1	I	I	
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	100	-	-	V
Gate-Body Leakage Current		I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	TJ=25℃		V 400V V 0V	-	-	1	μА
	TJ=100°C	IDSS	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	100	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.8	2.5	V
Drain-Source on-Resistance²		_	V <sub>GS</sub> = 10V, I <sub>D</sub> = 12A	-	13.5	17	
		R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	16.5	24	- mΩ
Forward Transconductance <sup>2</sup>		<b>G</b> fs	V <sub>DS</sub> = 5V, I <sub>D</sub> = 15A	-	41	-	S
Dynamic Characteristic	s		,	•		•	
Input Capacitance		Ciss		-	1190	-	
Output Capacitance  Reverse Transfer Capacitance		Coss	V <sub>DS</sub> = 50V, V <sub>GS</sub> =0V, f =1MHz	-	303	-	pF
		Crss		-	9.1	-	
Switching Characteristi	cs		,	•		•	
Gate Resistance		R <sub>G</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> =0V, f =1MHz	-	1.3	-	Ω
Total Gate Charge		Qg		-	18	-	nC
Gate-Source Charge		Qgs	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 50V, I <sub>D</sub> = 15A	-	5.2	-	
Gate-Drain Charge		Q <sub>gd</sub>		-	2.1	-	
Turn-on Delay Time		t <sub>d(on)</sub>		-	37	-	. nS
Rise Time		tr	V <sub>GS</sub> =10V, V <sub>DS</sub> = 50V,	-	9.3	-	
Turn-off Delay Time		t <sub>d(off)</sub>	$R_G = 3\Omega$ , $I_D = 15A$	-	50	-	
Fall Time		t <sub>f</sub>		-	13.6	-	
Drain-Source Body Dio	de Charact	eristics	,	•		l	
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1	V
Continuous Source Current <sup>1,5</sup>		Is	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-	-	30	Α
Body Diode Reverse Recovery Time		t <sub>rr</sub>	V <sub>R</sub> = 50V ,I <sub>F</sub> = 15A,	-	37.9	-	nS
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>	dI/dt = 500A/μs	_	40	_	nC

### Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =50V,  $V_{GS}$ =10V, L=0.5mH,  $I_{AS}$ =20A
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **Typical Characteristics**

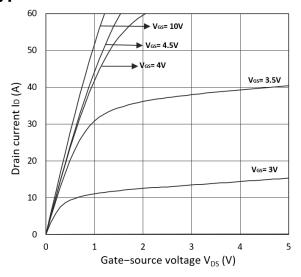


Figure 1. Output Characteristics

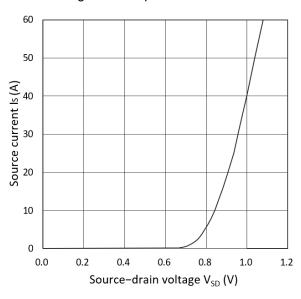


Figure 3. Forward Characteristics of Reverse

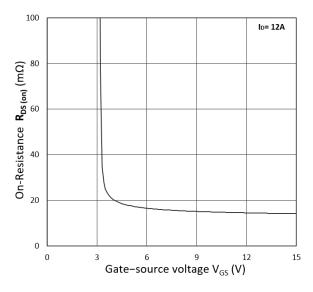


Figure 5.  $R_{DS(ON)}$  vs.  $V_{GS}$ 

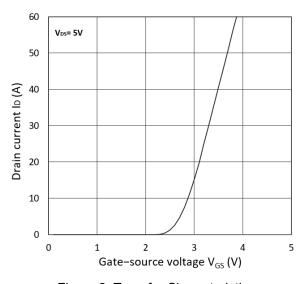


Figure 2. Transfer Characteristics

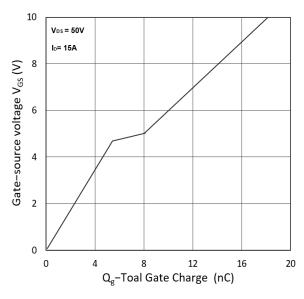


Figure 4. Gate Charge Characteristics

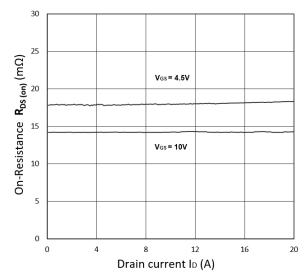
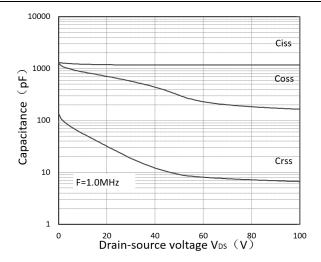


Figure 6. R<sub>DS(ON)</sub> vs. I<sub>D</sub>





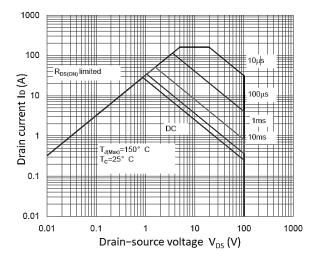


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

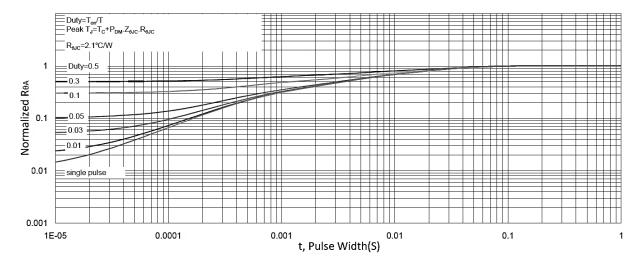


Figure 9. Normalized Maximum Transient Thermal Impedance

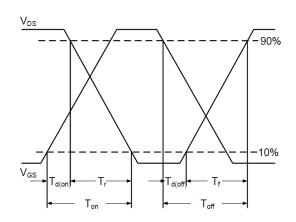


Figure 10. Switching Time Waveform

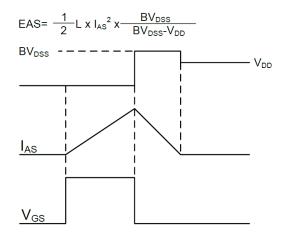
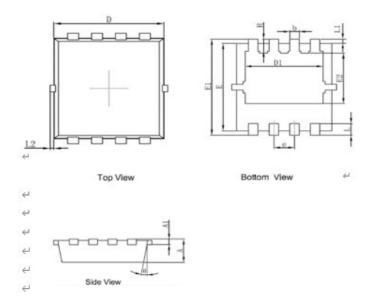


Figure 11. Unclamped Inductive Switching

Waveform



#### **Mechanical Dimensions for PDFN3030-8L**



#### **COMMON DIMENSIONS**

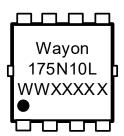
SYMBOL	MM			
STIVIDUL	MIN	MAX		
А	0.65	0.90		
A1	0.10	0.25		
D	2.90	3.25		
D1	2.25	2.69		
E	2.90	3.20		
E1	3.00	3.60		
E2	1.35	2.20		
b	0.20	0.40		
е	0.65BSC			
L	0.15	0.50		
L1	0.13BSC			
L2	0.00	0.20		
Н	0.15	0.65		
θ	0°	14°		



## **Ordering Information**

Part	Package	Marking	Packing method
WMQ175N10LG2	PDFN3030-8L	175N10L	Tape and Reel

### **Marking Information**



175N10L = Device code

WWXXXXX Date code

### **Contact Information**

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WAYON website: http://www.way-on.com

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